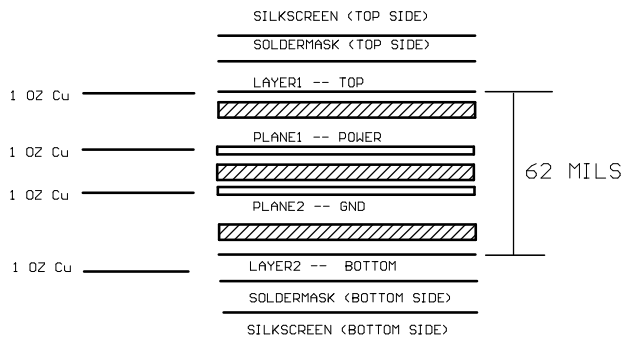
NOTES: (UNLESS OTHERWISE SPECIFIED)

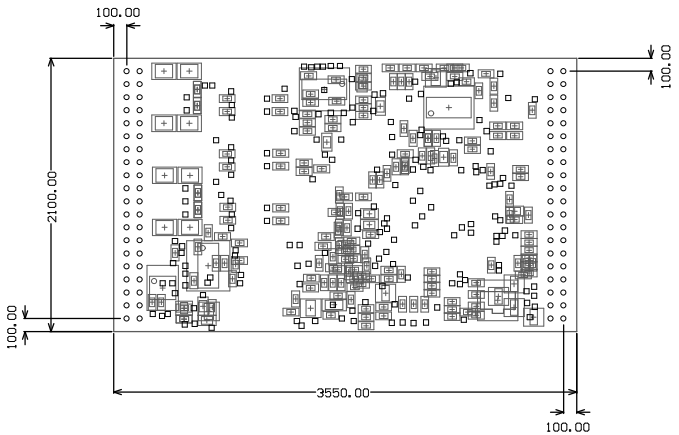
1. FABRICATE AS PER IPC-6012A TYPE2,CLASS2.
2. BOARD MATERIAL:FR4
3. BOARD FINISH:IMMERSION GOLD.
4. BOARD THICKNESS:62 MILS +/-5 MIL TOL.
5. APPLY SOLDER MASK ON BOTH SIDES USING LPI PROCESS,COLOR:BLUE/GREEN
6. APPLY SILKSCREEN LEGEND USING WHITE NON CONDUCTIVE EPOXY INK.
7. WARP AND TWIST SHOULD NOT EXCEED .005 INCH PER INCH IN ANY DIRECTION.
8. DIMENSIONAL LIMITS APPLY AFTER PLATING OR COATING.
9. MINIMUM PLATING ON ALL THE THROUGH HOLE SHALL BE 0.001 Cu.
10. NO VENDOR LOGO OR NAME ON THE BOARD
11. BOARD DIMENSIONS ARE IN MIL.
12. CLIP THE SILKSCREEN OVER SOLDERMASK
13. BOARD MUST BE FREE FROM VOIDS, PITS, SCRATCHES AND RESIDUE SUCH AS DIRT, GREASE ETC.
14. ALL MATERIAL USED MUST BE ROHS COMPLIANT
15. PCB VENDOR MUST NOTIFY RESPONSIBLE CYPRESS CONTACT OF ANY DISCREPANCIES BETWEEN FABRICATION DATA AND FABRICATION DRAWING
15. SMOOTHEN ALL ROUGH EDGES

| REVISIONS | DATE |
|---|---|
| REV ** | APR 2012 |
| REV *A | JUN 2012 |
| REV *B | NOV 2012 |
| REV *C | MAY 2013 |
| | |

LAYER STACKUP - 4 LAYER




| Symbol | Hit Count | Tool Size | Plated | Hole Type |
|---|---|---|---|---|
| □ | 173 | 15mil (0.381mm) | PTH | Round |
| ○ | 80 | 35.433mil (0.9mm) | PTH | Round |
| | 253 Total | | | |




LAYER FAB

CYPRESS SEMICONDUCTOR CORPORATION

198 CHAMPION CT, SAN JOSE, CA 95134

| TITLE: | PSoC 5LP - SOLAR MICROINVERTER CONTROL CARD | | |
|---|---|---|---|
| DRAWN BY | DATED | Drill Drawing. | REV |
| SNVN | MAY 2013 | FILM LAYERS ARE SHOWN AS VIEWED FROM THE TOP SIDE OF THE BOARD. | *C |
| | | UNITS: MIL | SIZE A3 |

